Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21	adhesive near3 porous and ((youngs elastic) adj modulus) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:34
L2	69	adhesive near5 (((triple three) adj layer) (double adj sided)) and ((youngs elastic) adj modulus) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:46
L3	4	adhesive near5 (((triple three) adj layer) (double adj sided)) and ((youngs elastic) adj modulus near3 temperature) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 12:54
L4	30	adhesive near12 ((youngs elastic) adj modulus near3 temperature) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 13:02
L5	0	adhesive near12 ((youngs elastic) adj modulus near3 -55)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:03
L6	0	adhesive near12 ((youngs elastic) adj modulus near5 -55)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:03
L7	0	adhesive near12 ((youngs elastic) adj modulus near5 -100)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 13:03
L8	1	adhesive near12 ((youngs elastic) adj modulus near5 -50)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:05

L9	0	adhesive near12 ((youngs elastic) adj modulus near5 -60)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:05
L10	0	adhesive near12 ((youngs elastic) adj modulus near5 -70)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:05
L11	0	adhesive near12 ((youngs elastic) adj modulus near5 -75)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 13:05
L12	2	adhesive near12 ((youngs elastic) adj modulus) near3 ((function versus) adj temperature) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:32
S1	0	circut adj tape and adhesive and ball adj grid adj array and ((dielectric adj film) same circuit) and elastic adj modulus and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:09
S2	0	circut adj tape and adhesive and ball adj grid adj array and elastic adj modulus and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/04/28 14:08
S3	0	circut adj tape and adhesive and ball adj grid adj array and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:08
S4	0	(circut adj tape) and adhesive and (ball adj grid adj array) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:09

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S5	0	(circut adj tape) and (ball adj grid adj array) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 12:17
S6	0	(circut adj tape) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:09
S7	0	adhesive and ball adj grid adj array and ((dielectric adj film) same circuit) and elastic adj modulus and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR.	ON	2005/04/28 14:10
S8	18811	ball adj grid adj array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ÓN	2005/04/28 14:10
S9	2392	circuit adj tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:10
S10	1271	S9 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:10
S11	6	S10 and (ball adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:22
S28	33	(ball adj grid adj array) and (tape near8 circuit\$3) and (elastic adj modulus)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:49

S29	2	S28 and @ad<"19960530" .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 14:57
S30	475	TBGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 15:09
S31	31	S30 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:41
S32	6349	TAB adj tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:41
S33	0	S32 and dielectric and porous and ((elastic young) adj modul\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:42
S34	2203	((elastic young\$2) adj modulus) and adhesive and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:43
S35	1100	S34 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:43
S36	115	S35 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:47

S41	74	(circuit adj tape) and BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/05/04 13:07
S42	3	S41 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 12:17
S43	2751	((circuit adj tape) TAB) and (BGA (ball adj grid adj array))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/04 13:08
S44	225	((circuit adj tape) TAB) and (BGA (ball adj grid adj array)) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 16:33
S45	6	S44 and adhesive adj film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:21
S46	20460	TGA (tab adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:22
S47	22	(tab adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/04 13:22
548	25	((tab tape) adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:22

S49	8	S48 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:28
S50	104	S44 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2005/05/04 13:35
S51	5	TGBA and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:36
S52	31	TBGA and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:41
S53	36	((circuit adj tape) TAB) same (BGA (ball adj grid adj array)) and @ad<"19960530" and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:16
S55	120613	(TAB (circuit adj tape) (flexible circuit\$3)) and porous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 09:24
S56	116276	((tape adj automated adj bonding) (circuit adj tape) (flexible circuit\$3)) and porous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 09:20
S57	34978	((tape adj automated adj bonding) (TAB) (circuit adj tape) (flexible circuit\$3)) and porous and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:20

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S58	4473	S57 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:20
S59	836	S58 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 09:21
S60	33	S59 and ((elastic Young\$2) adj modulus)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:24
S61	12466	(TAB (circuit adj tape) (flexible adj circuit\$3)) and porous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:24
S62	5895	(TAB (circuit adj tape) (flexible adj circuit\$3)) and porous and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:24
S63	1983	S62 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:24
S64	91	S63 and ((elastic Young\$2) adj modulus)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:25
S65	2	S64 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:52

S66	. 3	triple adj layer adj adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:30
S67	6	("5753362" "5836860" "6121553" "6184577" "6225418" "6265782").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/05 09:53
S68	12058	double adj side\$2 adj adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 09:55
S69	337	S68 and porous and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 10:00
S70	12	S69 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/05 10:04
S71	97	wire adj bond\$3 adj temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 10:04
S72	39	S71 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 10:22
S75	0	teraoka.as. and seisakusyo.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 07:29
S76	1700	teraoka.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:37

S77	130	seisakusyo.as.	US-PGPUB;	OR	ON	2005/05/06 07:29
			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB		,	
S78	9	S77 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:37
S79		seisakusyo.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:37
S80	9	S79 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:37
S81	187	teraoka.as. and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:14
S82	97	S81 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2005/05/06 07:39
S83	0	S82 and elastic adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 07:40
S84	0	S82 and youngs adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 07:40

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S96	193	adhesive and ((youngs elastic) adj modulus) near5 (room adj temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:10
S97	40	S96 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:50
S98	14	adhesive and ((youngs elastic) adj modulus) near5 function near3 temperature and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 09:13
S99	4	adhesive and ((youngs elastic) adj modulus) near5 versus near3 temperature and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:13
S10 0	26	triple adj layer near3 adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:33
S10 1	12	S100 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 09:30
S10 2	849	(triple three) adj layer near3 adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 09:33
S10 3	351	S102 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:34

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S10 4	40	S103 and modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:41
S10 5	19068	Shinetsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 09:42
S10 6	1521	S105 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/06 09:42
S10 7	907	S106 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:42
S10 8	8	S107 and modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2005/05/06 09:42